

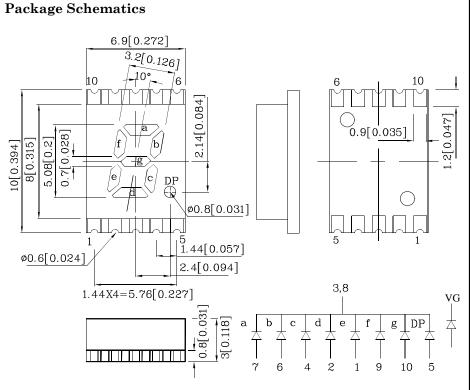
Part Number: XZFVG05C

SURFACE MOUNT DISPLAY

Features

- $\bullet~0.2$ inch digit height
- \bullet Robust package
- Low power consumption
- Standard configuration: Gray face w/ white segments
- Standard Package: 650pcs/ Reel
- MSL (Moisture Sensitivity Level): 2a
- RoHS compliant







1. All dimensions are in millimeters (inches), Tolerance is $\pm 0.25 (0.01") unless otherwise noted.$

2. Specifications are subject to change without notice.

3. The gap between the reflector and PCB shall not exceed $0.25 \mathrm{mm}.$

Absolute Maximum Ratings (T _A =25°C)	VG (AlGaInP)	Unit		
Reverse Voltage	V_{R}	5	V	
Forward Current	$\mathbf{I}_{\mathbf{F}}$	30	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	$i_{\rm FS}$	150	mA	
Power Dissipation	P_{D}	75	mW	
Operating Temperature	TA	$-40 \sim +85$	°C	
Storage Temperature	Tstg	$-40 \sim +85$	U	

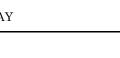
Operating Characteristics (T _A =25°C)		VG (AlGaInP)	Unit	
Forward Voltage (Typ.) (I _F =10mA)	$V_{\rm F}$	2	V	
Forward Voltage (Max.) (I _F =10mA)	$V_{\rm F}$	2.5	V	
Reverse Current (Max.) (V _R =5V)	I_R	10	uA	
Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =10mA)	λP	574*	nm	
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I _F =10mA)	λD	570*	nm	
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =10mA)	$ riangle\lambda$	20	nm	
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	15	pF	
Luminous Intensity Wavelength CIE127-2007* CIE127-2007* (I _F =10mA) ucd nm λP		Description		
min. typ.				
3600 11990 2200* 4290* 574*	Common Cathode, Rt. Hand Decimal			

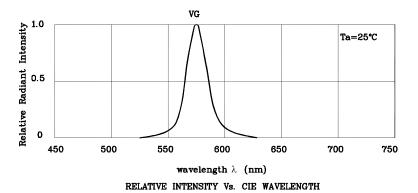
	Part umber	Emitting Color	Emitting Material	CIE127- (I _F =10m.		CIE127-2007* nm λP	Description
				min.	typ.		
XZF	FVG05C	Green	AlGaInP	3600 2200*	11990 4290*	574*	Common Cathode, Rt. Hand Decimal.

*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards. Jan 06.2014

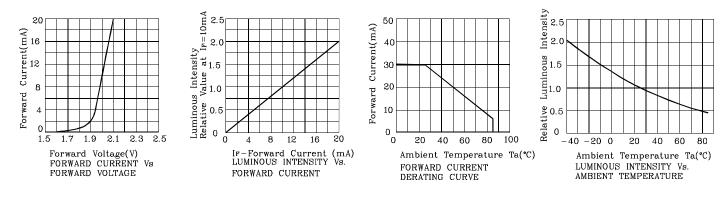
XDSA9204 V6-X Layout: Maggie L.





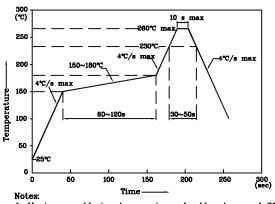


♦ VG



LED is recommended for reflow soldering and soldering profile is shown below.

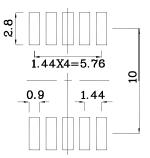
Reflow Soldering Profile for SMD Products (Pb-Free Components)



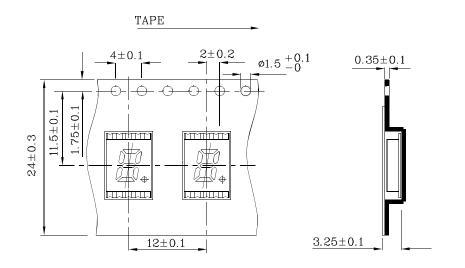
- 1. Maximum soldering temperature should not exceed 260°C
- 2. Recommended reflow temperature: 145°C-260°C Do not put stress to the epoxy resin during
- З. high temperatures conditions



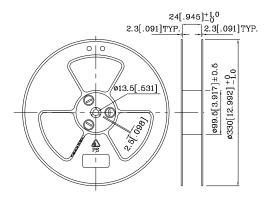
Recommended Soldering Pattern (Units : mm; Tolerance: ±0.15)



Tape Specification (Units : mm)



Reel Dimension



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm

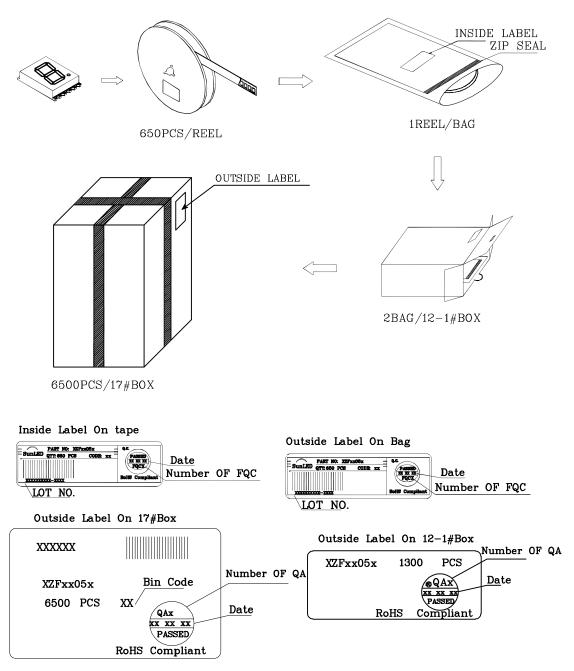
2. Luminous intensity / luminous flux: +/-15\%

3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.



PACKING & LABEL SPECIFICATIONS



TERMS OF USE

- 1. Data presented in this document reflect statistical figures and should be treated as technical reference only.
- 2. Contents within this document are subject to improvement and enhancement changes without notice.
- 3. The product(s) in this document are designed to be operated within the electrical and environmental specifications indicated on the datasheet. User accepts full risk and responsibility when operating the product(s) beyond their intended specifications.
- 4. The product(s) described in this document are intended for electronic applications in which a person's life is not reliant upon the LED. Please consult with a SunLED representative for special applications where the LED may have a direct impact on a person's life.
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- 6. Additional technical notes are available at http://www.SunLEDusa.com/TechnicalNotes.asp